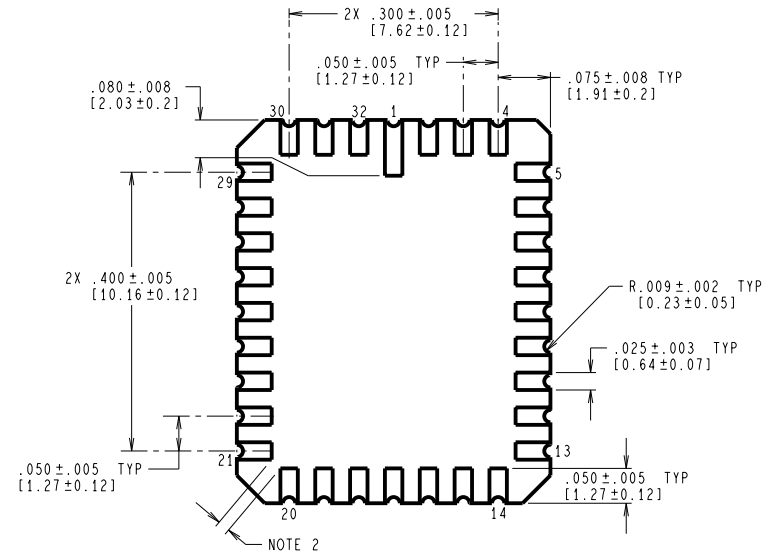
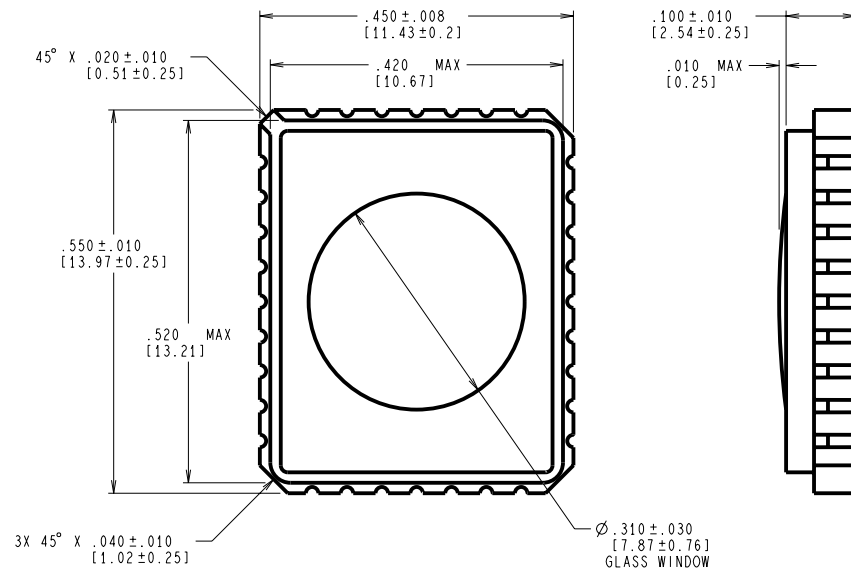


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW PER NEW STANDARD.	10235	02/27/94	DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 50 MICROINCHES/12.7 MICROMETERS MINIMUM GOLD PLATING OVER 50-350 MICROINCHES/1.27-8.89 MICROMETERS NICKEL.
 - SOLDER DIP.
SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.
- CORNER PADS MAY HAVE A 45° X .020 IN/0.51mm MAXIMUM CHAMFER TO ACCOMPLISH THE .015 IN/0.38mm DIMENSION.
- REFERENCE JEDEC REGISTRATION MO-041, VARIATION AB, DATED 8/86.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL/AERO
CONFIGURATION CONTROL

MIL-M-38510
CONFIGURATION CONTROL

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN	Dwayne Grady	02/27/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.			LEADLESS CHIP CARRIER, TYPE C, 32 TERMINAL		
ENGR. CHK.					
APPROVAL					
PROJECTION			SCALE	SIZE	DRAWING NUMBER
INCH [MM]			N/A	C	MKT-E32A
DO NOT SCALE DRAWING			SHEET 1 of 1		